

# Four-Channel, High Speed, $\pm 75V$ 1.25A Ultrasound Pulsers

## Features

- ▶ HVCMOS technology for high performance
- ▶ High density integration ultrasound transmitter
- ▶ 0 to  $\pm 75V$  output voltage
- ▶  $\pm 1.25A$  source and sink current in pulse mode
- ▶  $\pm 400mA$  source and sink current in CW mode
- ▶ Up to 20MHz operating frequency
- ▶ Matched delay times
- ▶ 1.2V to 5.0V CMOS logic interface
- ▶ Built-in output drain bleed resistors

## Application

- ▶ Portable medical ultrasound imaging
- ▶ Piezoelectric transducer drivers
- ▶ NDT ultrasound transmission
- ▶ Pulse waveform generator

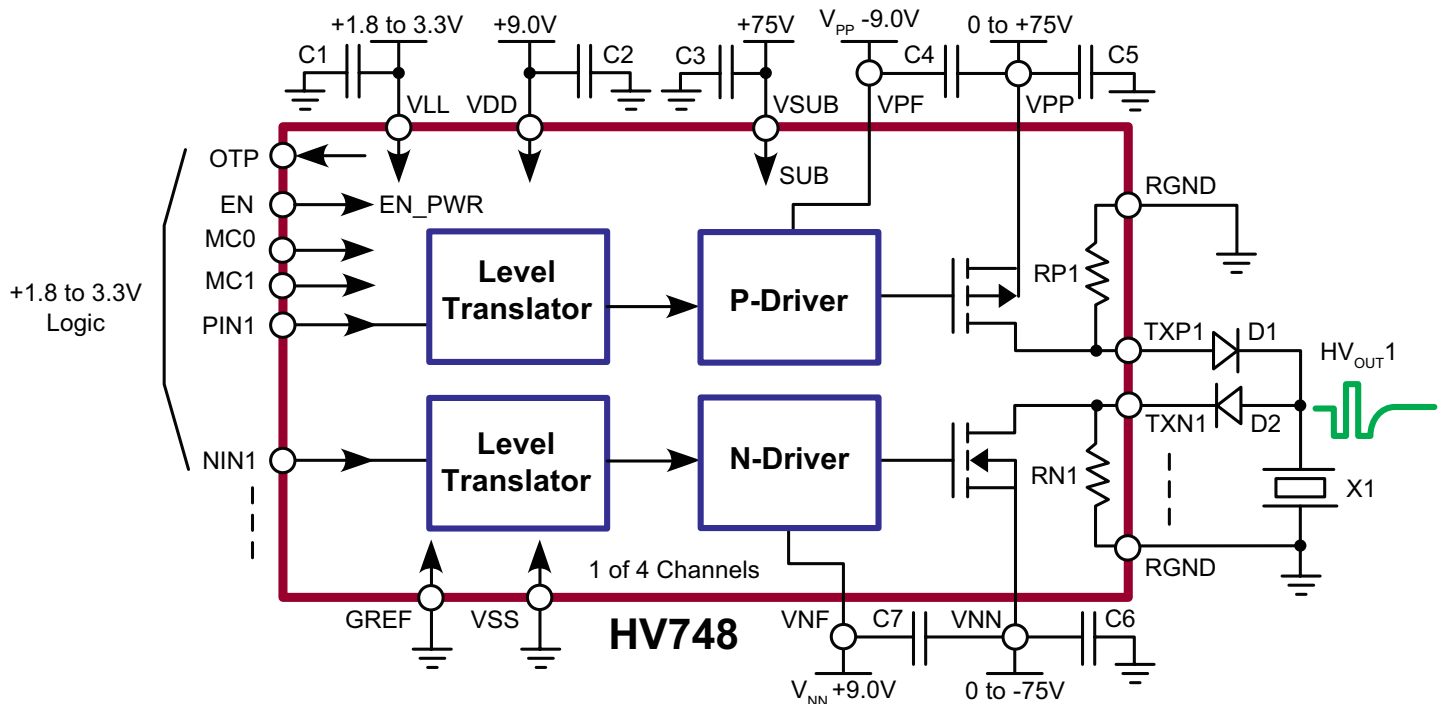
## General Description

The Supertex HV748 is a four-channel, monolithic, high voltage, high speed pulse generator. It is designed for portable medical ultrasound applications. This high voltage and high speed integrated circuit can also be used for piezoelectric, capacitive or MEMS sensing in ultrasonic nondestructive detection and sonar ranger applications.

The HV748 consists of a controller logic interface circuit, level translators, MOSFET gate drives and high power P-channel and N-channel MOSFETs as the output stage for each channel.

The output stages of each channel are designed to provide peak output currents over  $\pm 1.8A$  for pulsing, when in mode 4, with up to  $\pm 75$  volt swings. When in mode 1, all the output stages drop the peak current to  $\pm 400mA$  for low-voltage CW mode operation to decrease the power consumption of the IC. The P and N type of power FETs gate drivers are supplied by two floating 9.0VDC power supplies reference to  $V_{PP}$  and  $V_{NN}$ . This direct coupling topology of the gate drivers not only eliminates two high voltage capacitors per channel, but also makes the PCB layout easier.

## Typical Application Circuit



## Ordering Information

Part Number	Package Option	Packing
HV748K6-G	48-Lead QFN (7x7mm)	260/Tray

-G indicates package is RoHS compliant ('Green')



## Absolute Maximum Ratings

Parameter	Value
$V_{SS}$ , Power supply reference	0V
$V_{LL}$ , Positive logic supply	-0.5V to +7.0V
$V_{DD}$ , Positive logic and level translator supply	-0.5V to +14V
$(V_{PP} - V_{PF})$ Positive floating gate drive supply	-0.5V to +14V
$(V_{NF} - V_{NN})$ Negative gate floating drive supply	-0.5V to +14V
$(V_{PP} - V_{NN})$ Differential high voltage supply	+170V
$V_{PP}$ , High voltage positive supply	-0.5V to +85V
$V_{NN}$ , High voltage negative supply	+0.5V to -85V
OTP, Over Temperature Protection output	-0.5V to +7.0V
All logic input $PIN_x$ , $NIN_x$ and EN voltages	-0.5V to +7.0V
$(V_{SUB} - V_{SS})$ Substrate to $V_{SS}$ voltage difference	+170V
$(V_{PP} - TXP_x)$ $V_{PP}$ to $TXP_x$ voltage difference	+170V
$(V_{SUB} - TXP_x)$ Substrate to $TXP_x$ voltage difference	+170V
$(TXN_x - V_{NN})$ $TXN_x$ to $V_{NN}$ voltage difference	+170V
Operating temperature	-40°C to 125°C
Storage temperature	-65°C to 150°C
Thermal resistance, $\theta_{JA}$	29°C/W
Thermal resistance, $\theta_{JC}$ (junction to thermal pad)	0.5°C/W

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

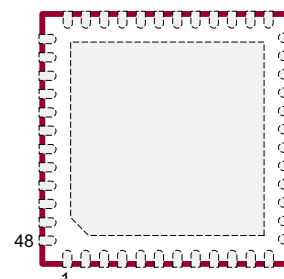
## Power-Up Sequence

Step	Description
1	$V_{SUB}$
2	$V_{LL}$ with logic signal low
3	$V_{DD}$
4	$(V_{PP} - V_{PF})$ and $(V_{NF} - V_{NN})$
5	$V_{PP}$ and $V_{NN}$
6	Logic control signals

## Power-Down Sequence

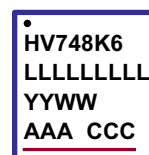
Step	Description
1	All logic signals go to low
2	$V_{PP}$ and $V_{NN}$
3	$(V_{PP} - V_{PF})$ and $(V_{NF} - V_{NN})$
4	$V_{DD}$
5	$V_{LL}$
6	$V_{SUB}$

## Pin Configuration



**48-Lead QFN**  
(top view)

## Package Marking



L = Lot Number  
 YY = Year Sealed  
 WW = Week Sealed  
 A = Assembler ID  
 C = Country of Origin  
 — = "Green" Packaging

Package may or may not include the following marks: Si or

**48-Lead QFN**

## Typical Thermal Resistance

Package	$\theta_{ja}$
48-Lead QFN	18°C/W

## Operating Supply Voltages and Current (4 Channel Active)

(Operating conditions, unless otherwise specified,  $V_{SS} = 0V$ ,  $V_{LL} = +3.3V$ ,  $V_{DD} = +9.0V$ ,  $V_{PP} - V_{PF} = +9.0V$ ,  $V_{NN} - V_{NF} = -9.0V$ ,  $V_{PP} = +75V$ ,  $V_{NN} = -75V$ ,  $T_A = 25^\circ C$ )

Sym	Parameter	Min	Typ	Max	Units	Conditions
$V_{LL}$	Logic voltage reference	1.2	1.8 to 3.3	5.0	V	---
$V_{DD}$	Internal voltage supply	8.0	9.0	12	V	---
$V_{PF}$	Positive gate driver supply	$(V_{PP} - 12)$	$(V_{PP} - 9.0)$	$(V_{PP} - 8.0)$	V	Floating driver voltage supplies.
$V_{NF}$	Negative gate drive supply	$(V_{NN} + 8.0)$	$(V_{NN} + 9.0)$	$(V_{NN} + 12.0)$	V	
$V_{SUB}$	IC substrate voltage	$V_{DD}$	$V_{PP}$	+75	V	Must be the most positive potential of the IC.
$V_{PP}$	Positive HV supply	0	-	+75	V	---
$V_{NN}$	Negative HV supply	-75	-	0	V	---
$SR_{MAX}$	Slew rate limit of $V_{PP}$ , $V_{NN}$	-	-	25	V/ $\mu s$	Built-in slew rate detection protection.
$I_{LL}$	$V_{LL}$ Current EN = Low	-	35	120	$\mu A$	---
$I_{DDQ}$	$V_{DD}$ Current EN = Low	-	15	-	$\mu A$	---
$I_{DDEN}$	$V_{DD}$ Current EN = High	-	0.75	2.0	mA	f = 0MHz
$I_{DDEN}$	$V_{DD}$ Current MODE = 4	-	0.75	-	mA	f = 5.0MHz, continuous, no loads
$I_{DDENCW}$	$V_{DD}$ Current MODE = 1	-	2.0	-	mA	
$I_{PPQ}$	$V_{PP}$ Current EN = Low	-	10	25	$\mu A$	f = 0MHz
$I_{PPEN}$	$V_{PP}$ Current MODE = 4	-	250	-	mA	f = 5.0MHz, continuous, no loads
$I_{PPENCW}$	$V_{PP}$ Current MODE = 1	-	170	-	mA	
$I_{NNQ}$	$V_{NN}$ Current EN = Low	-	15	30	$\mu A$	f = 0MHz
$I_{NNEN}$	$V_{NN}$ Current MODE = 4	-	250	-	mA	f = 5.0MHz, continuous, no loads
$I_{NNENCW}$	$V_{NN}$ Current MODE = 1	-	170	-	mA	
$I_{PFQ}$	$V_{PF}$ Current EN = Low	-	10	25	$\mu A$	f = 0MHz
$I_{PFEN}$	$V_{PF}$ Current MODE = 4	-	50	-	mA	f = 5.0MHz, continuous, no loads
$I_{PFENCW}$	$V_{PF}$ Current MODE = 1	-	12	-	mA	
$I_{NFQ}$	$V_{NF}$ Current EN = Low	-	20	30	$\mu A$	f = 0MHz
$I_{NFEN}$	$V_{NF}$ Current MODE = 4	-	25	-	mA	f = 5.0MHz, continuous, no loads
$I_{NFENCW}$	$V_{NF}$ Current MODE = 1	-	12	-	mA	

### Note:

All supply current values are for reference only.

## Under Voltage and Over Temperature Protection

Sym	Parameter	Min	Typ	Max	Units	Conditions
$V_{PULL\_UP}$	Open drain pull-up voltage	-	-	5.0	V	---
$V_{UVDD}$	$V_{DD}$ threshold	3.5	-	6.5	V	---
$V_{UVLL}$	$V_{LL}$ threshold	0.7	-	1.0	V	---
$V_{UVVF}$	$V_{PF}$ , $V_{NF}$ threshold	3.5	-	6.5	V	---
$V_{OL\_OTP}$	OTP flag output low voltage	-	-	1.0	V	$V_{LL} = 3.3V$ , OTP = Active, $I_{PULL\_UP} = 1.0mA$ .
$I_{OTP}$	Max. open drain output current	-	1.0	-	mA	---
$T_{OTP}$	Over-temperature threshold	95	110	125	$^\circ C$	If over-temperature occurred, OTP low and all TX outputs will be HiZ.
$T_{HYS}$	OTP output reset hysteresis	-	7.0	-		

## DC Electrical Characteristics

(Operating conditions, unless otherwise specified,  $V_{SS} = 0V$ ,  $V_{LL} = +3.3V$ ,  $V_{DD} = +9V$ ,  $V_{PF} = V_{PP} - 9V$ ,  $V_{NF} = V_{NN} + 9V$ ,  $V_{PP} = +75V$ ,  $V_{NN} = -75V$ ,  $T_A = 25^\circ C$ )

### Output P-Channel MOSFET, TXP (Mode 4)

Sym	Parameter	Min	Typ	Max	Units	Conditions
$I_{OUT}$	Output saturation current	1.25	1.8	-	A	---
$R_{ON}$	Channel resistance	-	8.0	-	$\Omega$	$I_{SD} = 100mA$
$C_{OSS}$	Output capacitance	-	100*	-	pF	$V_{DS} = 25V$ , $f = 1.0MHz$

### Output N-Channel MOSFET, TXN (Mode 4)

Sym	Parameter	Min	Typ	Max	Units	Conditions
$I_{OUT}$	Output saturation current	1.25	1.8	-	A	---
$R_{ON}$	Channel resistance	-	7.5	-	$\Omega$	$I_{SD} = 100mA$
$C_{OSS}$	Output capacitance	-	40*	-	pF	$V_{DS} = 25V$ , $f = 1.0MHz$

### MOSFET Drain Bleed Resistor

Sym	Parameter	Min	Typ	Max	Units	Conditions
$R_{P/N1-4}$	Output bleed resistance	10	15	30	k $\Omega$	---
$P_{RO}$	Bleed resistors power limit	-	-	40	mW	---

### Logic Inputs

Sym	Parameter	Min	Typ	Max	Units	Conditions
$V_{IH}$	Input logic high voltage	$(V_{LL} - 0.4)$	-	$V_{LL}$	V	---
$V_{IL}$	Input logic low voltage	0	-	0.4	V	---
$I_{IH}$	Input logic high current	-	-	10	$\mu A$	---
$I_{IL}$	Input logic low current	-10	-	-	$\mu A$	---
$C_{IN}$	Input logic capacitance	-	-	5.0*	pF	---

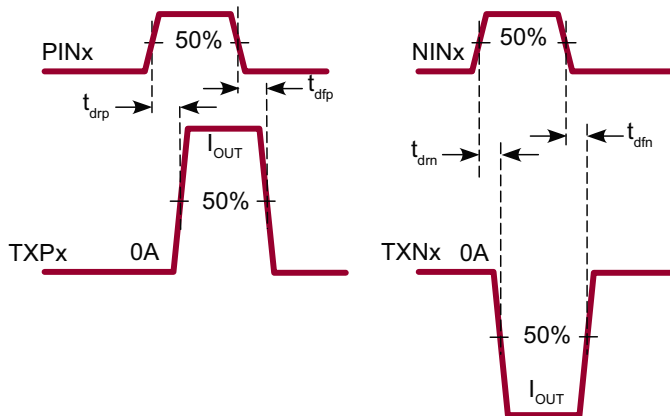
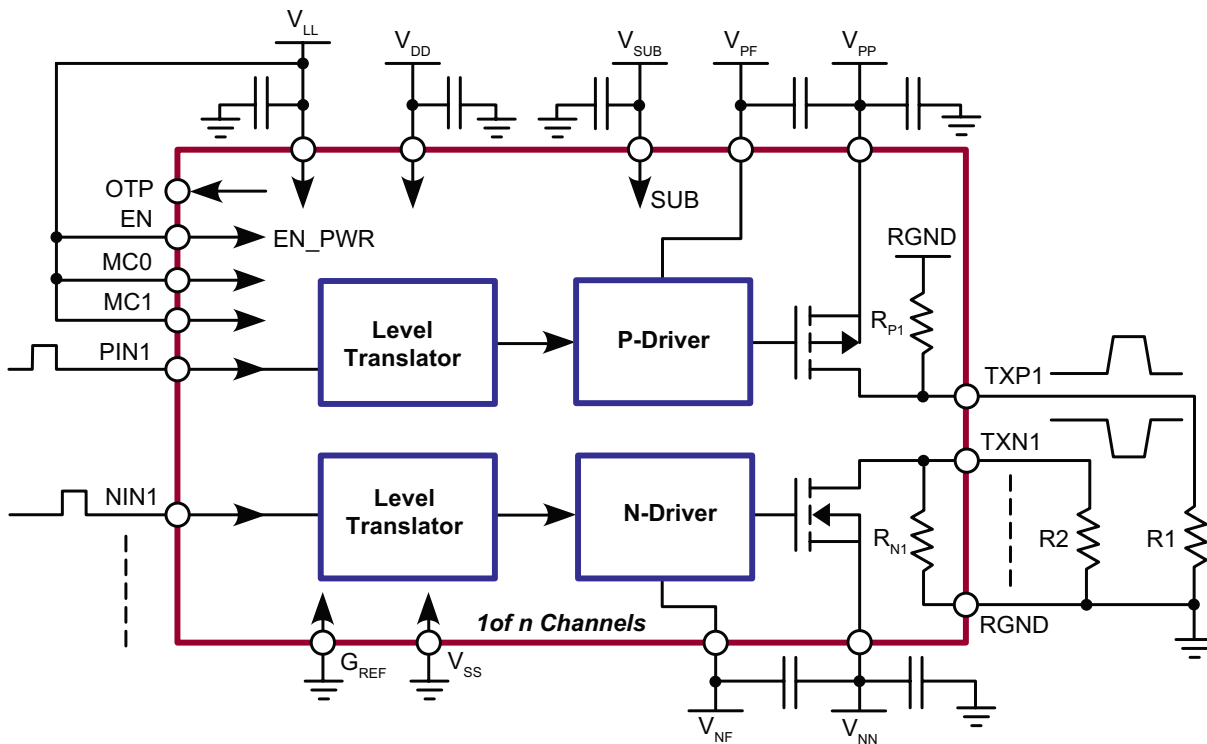
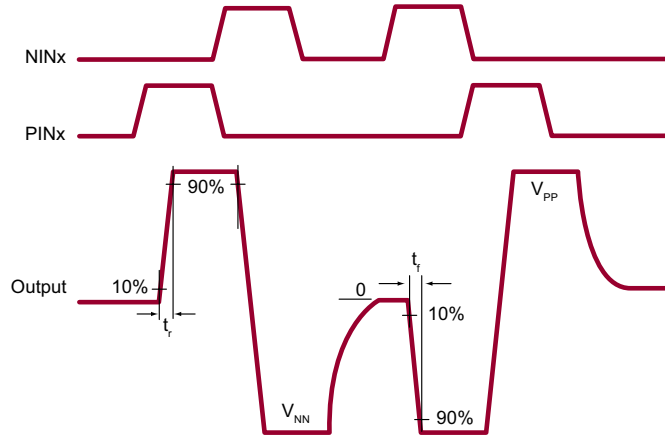
## AC Electrical Characteristics

(Operating conditions, unless otherwise specified,  $V_{SS} = 0V$ ,  $V_{LL} = +3.3V$ ,  $V_{DD} = +9V$ ,  $V_{PF} = (V_{PP} - 9V)$ ,  $V_{NF} = (V_{NN} + 9V)$ ,  $V_{PP} = +75V$ ,  $V_{NN} = -75V$ ,  $T_A = 25^\circ C$ )

Sym	Parameter	Min	Typ	Max	Units	Conditions
$t_r$	Output rise time	-	35	-	ns	330pF//2.5k $\Omega$ load
$t_f$	Output fall time	-	43	-	ns	
$f_{OUT}$	Output frequency range	-	-	20	MHz	100 $\Omega$ resistor load
HD2	Second harmonic distortion	-	-40*	-	dB	
$t_{EN}$	Enable time	-	180	500	$\mu s$	
$t_{DIS}$	Disable time	-	2.8	10	$\mu s$	3.9 $\Omega$ resistor load (see timing diagram)
$t_{dr}$	Delay time on inputs rise	-	18	-	ns	
$t_{df}$	Delay time on inputs fall	-	18	-	ns	
$\Delta t_{DELAY}$	Delay time matching	-	$\pm 2.0$	-	ns	P to N, channel to channel
$t_{dm}$	Delay on mode change	-	2.5	10	$\mu s$	100 $\Omega$ resistor load
$t_j$	Delay jitter on rise or fall	-	15*	-	ps	$V_{PP}/V_{NN} = \pm 25V$ , input $t_r$ 50% to $HV_{OUT}$ $t_r$ or $t_f$ 50%, with 330pF//2.5k $\Omega$ load

\* Guaranteed by design.

# Switch AC Test Timing Diagram



## Truth Table (All Modes)

Logic Inputs			Output	
EN	PIN <sub>x</sub>	NIN <sub>x</sub>	TXP <sub>x</sub>	TXN <sub>x</sub>
1	0	0	OFF	OFF
1	1	0	ON	OFF
1	0	1	OFF	ON
1	1	1	ON†	ON†
0	X	X	OFF	OFF

† Not allowed, may damage IC.

## Drive Mode Control Table

Mode	MC1	MC0	I <sub>SC</sub> (A)	R <sub>ONP</sub> (Ω)	R <sub>ONN</sub> (Ω)
1	0	0	0.41	35	33
2	0	1	0.58	25	23
3	1	0	0.97	15	14
4	1	1	1.8	8.0	7.5

## Notes:

- $V_{PF}/V_{NN} = +/-75V$ ,  $V_{DD} = (V_{PP} - V_{PF}) = (V_{NF} - V_{NN}) = +9.0V$
- $I_{SC}$  is current into  $1.0\Omega$  to GND
- $R_{ON}$  calculated from  $V_{OUT}$  into  $100\Omega$  load

## Pin Descriptions

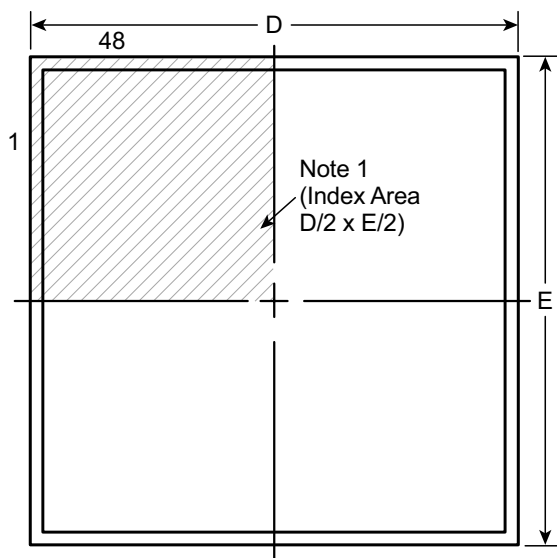
Pin #	Name	Function
1	VDD	Positive internal voltage supply (+9.0V).
2	VSS	Power supply return (0V).
3	PIN1	Input logic control of high voltage output P-FET of channel 1, Hi = on, Low = off.
4	NIN1	Input logic control of high voltage output N-FET of channel 1, Hi = on, Low = off.
5	PIN2	Input logic control of high voltage output P-FET of channel 2, Hi = on, Low = off.
6	NIN2	Input logic control of high voltage output N-FET of channel 2, Hi = on, Low = off.
7	PIN3	Input logic control of high voltage output P-FET of channel 3, Hi = on, Low = off.
8	NIN3	Input logic control of high voltage output N-FET of channel 3, Hi = on, Low = off.
9	PIN4	Input logic control of high voltage output P-FET of channel 4, Hi = on, Low = off.
10	NIN4	Input logic control of high voltage output N-FET of channel 4, Hi = on, Low = off.
11	VSS	Power supply return (0V).
12	VDD	Positive internal voltage supply (+9.0V).
13	OTP	Over temperature protection output, open N-FET drain, active low if IC temperature >110°C.
14	MC1	Output current mode control pins, see Drive Mode Control Table.
15	MC0	
16	Thermal Pad (VSUB)	Substrate of the IC, Substrate bottom is internally connected to the central thermal pad on the bottom of package. It must be connected to VSUB, the most positive potential of the IC externally.

## Pin Descriptions (cont.)

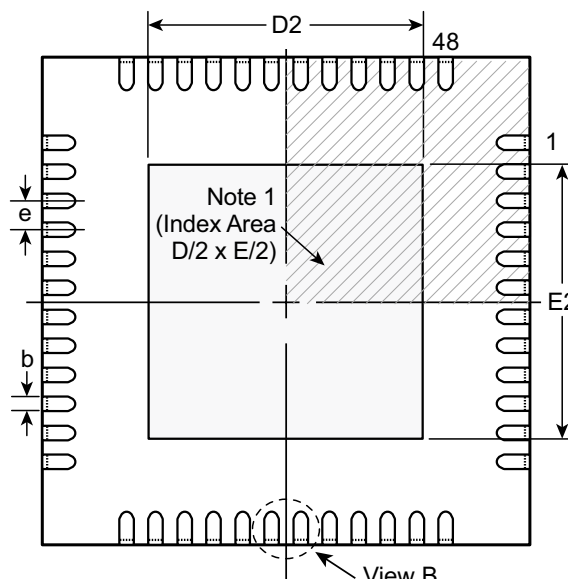
Pin #	Name	Function
17	VPF	P-FET drive floating power supply, $(V_{PP} - V_{PF}) = +9.0V$ .
18	VPP	Positive high voltage power supply (+75V).
19		
20		
21	VNN	Negative high voltage power supply (-75V).
22		
23		
24	VNF	N-FET drive floating power supply, $(V_{NF} - V_{NN}) = +9.0V$ .
25	Thermal Pad (VSUB)	Substrate of the IC, Substrate bottom is internally connected to the central thermal pad on the bottom of package. It must be connected to VSUB, the most positive potential of the IC externally.
26	RGND	Bleed resistors common return ground. (Both pins must be used)
27	TXN4	Output N-FET drain (open drain output) for channel 4.
28	TXP4	Output P-FET drain (open drain output) for channel 4.
29	TXN3	Output N-FET drain (open drain output) for channel 3.
30	TXP3	Output P-FET drain (open drain output) for channel 3.
31	TXN2	Output N-FET drain (open drain output) for channel 2.
32	TXP2	Output P-FET drain (open drain output) for channel 2.
33	TXN1	Output N-FET drain (open drain output) for channel 1.
34	TXP1	Output P-FET drain (open drain output) for channel 1.
35	RGND	Bleed resistors common return ground. (Both pins must be used)
36	Thermal Pad (VSUB)	Substrate of the IC, Substrate bottom is internally connected to the central thermal pad on the bottom of package. It must be connected to VSUB, the most positive potential of the IC externally.
37	VNF	N-FET drive floating power supply, $(V_{NF} - V_{NN}) = +9.0V$ .
38	VNN	Negative high voltage power supply (-75V).
39		
40		
41	VPP	Positive high voltage power supply (+75V).
42		
43		
44	VPF	P-FET drive floating power supply, $(V_{PP} - V_{PF}) = +9.0V$ .
45	Thermal Pad (VSUB)	Substrate of the IC, Substrate bottom is internally connected to the central thermal pad on the bottom of package. It must be connected to VSUB, the most positive potential of the IC externally.
46	EN	Chip power enable Hi = on, Low = off.
47	GRES	Logic Low reference, logic ground (0V).
48	VLL	Logic Hi voltage reference input (+3.3V).

# 48-Lead QFN Package Outline (K6)

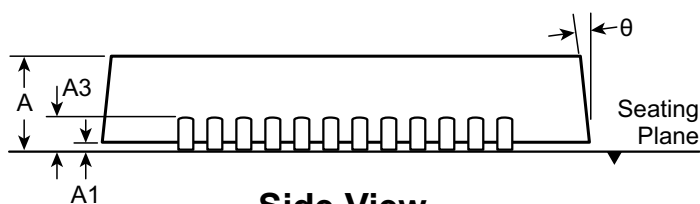
7.00x7.00mm body, 1.00mm height (max), 0.50mm pitch



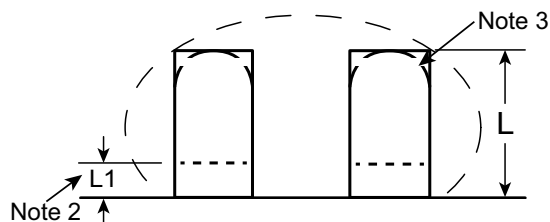
**Top View**



**Bottom View**



**Side View**



**View B**

**Notes:**

1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.
2. Depending on the method of manufacturing, a maximum of 0.15mm pullback (L1) may be present.
3. The inner tip of the lead may be either rounded or square.

Symbol	A	A1	A3	b	D	D2	E	E2	e	L	L1	θ	
Dimension (mm)	MIN	0.80	0.00	0.20 REF	0.18	6.85*	1.25	6.85*	1.25	0.50 BSC	0.30 <sup>†</sup>	0.00	0°
	NOM	0.90	0.02		0.25	7.00	-	7.00	-		0.40 <sup>†</sup>	-	-
	MAX	1.00	0.05		0.30	7.15*	5.45	7.15*	5.45		0.50 <sup>†</sup>	0.15	14°

JEDEC Registration MO-220, Variation VKKD-6, Issue K, June 2006.

\* This dimension is not specified in the JEDEC drawing.

† This dimension differs from the JEDEC drawing.

Drawings are not to scale.

Supertex Doc.#: DSPD-48QFNK67X7P050, Version C041009.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <http://www.supertex.com/packaging.html>.)

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